US 20240213386A1

(19) United States

(12) Patent Application Publication (10) Pub. No.: US 2024/0213386 A1

Zhang et al. (43) Pub. Date: Jun. 27, 2024

(54) **ENCAPSULANT SHEET WITH LOW POTENTIAL INDUCED DEGRADATION**

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(21) Appl. No.: **18/254,591**

(22) PCT Filed: **Dec. 17, 2020**

(86) PCT No.: **PCT/CN2020/137367**

§ 371 (c)(1),
(2) Date: **May 25, 2023**

Publication Classification

(51) **Int. Cl.**
H01L 31/048 (2014.01)
H01L 31/18 (2006.01)

(52) **U.S. Cl.**
CPC ***H01L 31/0481*** (2013.01); ***H01L 31/186*** (2013.01)

(57) **ABSTRACT**

An encapsulant sheet includes a material formed from an ethylene/C_4-C_8α-olefin copolymer having a resin volume resistivity (VR) from greater than $1\times10^{14}\Omega$ cm at 60° C. to less than $1\times10^{16}\Omega$ cm at 60° C. and from 0.01 wt % to 0.2 wt % of an ion scavenger. The encapsulant sheet has a transmittance greater than 91%. A photovoltaic module (**10**) includes a front encapsulant sheet (**12***a*) and a rear encapsulant sheet (**12***b*) composed of the material. The photovoltaic module (**10**) has a power loss after potential induced degradation (PID) test from 0.05% to less than 5%.